



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **KIRA, et al.**

Group Art Unit: 2652

Serial No.: 09/548,313

Examiner: **Craig A. Renner**

Filed: **April 12, 2000**

P.T.O. Confirmation No.: 6169

For: **HEAD ASSEMBLY HAVING INTEGRATED CIRCUIT CHIP COVERED BY
LAYER WHICH PREVENTS FOREIGN PARTICLE GENERATION**

RESPONSE UNDER 37 CFR §1.116

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JUN 03 2003

MAILSTOP AF

Technology Center 2600

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

May 29, 2003

Sir:

In response to the Office Action dated **January 29, 2003**, extended to **May 29, 2003** by a
one month Petition for Extension of Time, please amend the above-identified application as follows:

IN THE CLAIMS:

Amend the claims to read as follows:

1. (Twice Amended) A head assembly comprising:

a mounting surface;

an integrated circuit chip which is mounted on the mounting surface and processes signals;

and

a head slider which is provided with a head and is mounted on the mounting surface,

said integrated circuit chip being covered by a layer,

a height of the integrated circuit chip, including the layer, being lower than a height of the

*Do not
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APR 6-11-03*